

- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
- ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A->SIGNAL CONTACT->MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
- 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
- ④ IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)  
REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
- ⑤ THIS IS PACKAGED IN TRAY. (40pcs/TRAY)
- 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
- 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm LEAD AREA:GOLD 0.03 μm UNDER PLATING:NICKEL 1.3 μm		5	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm	
2	POLYAMIDE	BLACK UL94V-0		4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm	
1	POLYAMIDE	BLACK UL94V-0					

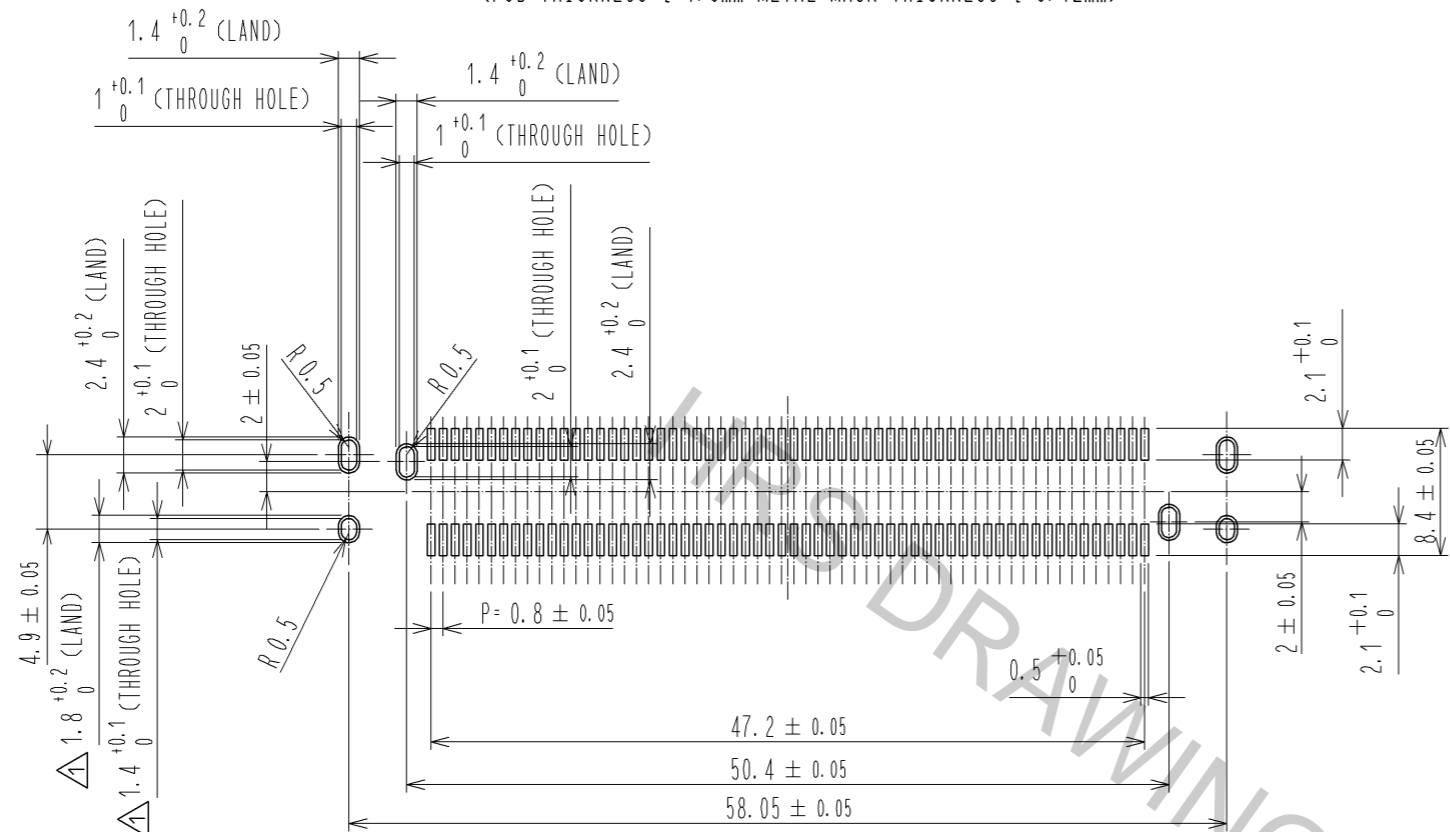
  

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	4	DIS-F-005578	TH. SANO	KI. HIROKAWA	11.07.21

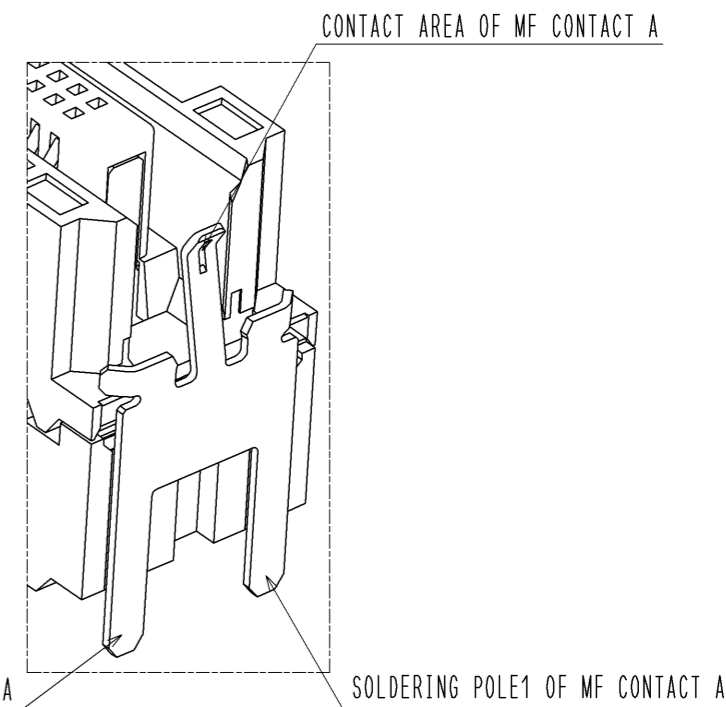
APPROVED	HS. OKAWA	11.03.17	DRAWING NO.	EDC3-334389-00
CHECKED	KI. HIROKAWA	11.03.17	PART NO.	FX18-120S-0.8SV15
DESIGNED	TH. SANO	11.03.17	CODE NO.	CL579-0029-1-00
DRAWN	TH. SANO	11.03.17		

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)  
(PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)

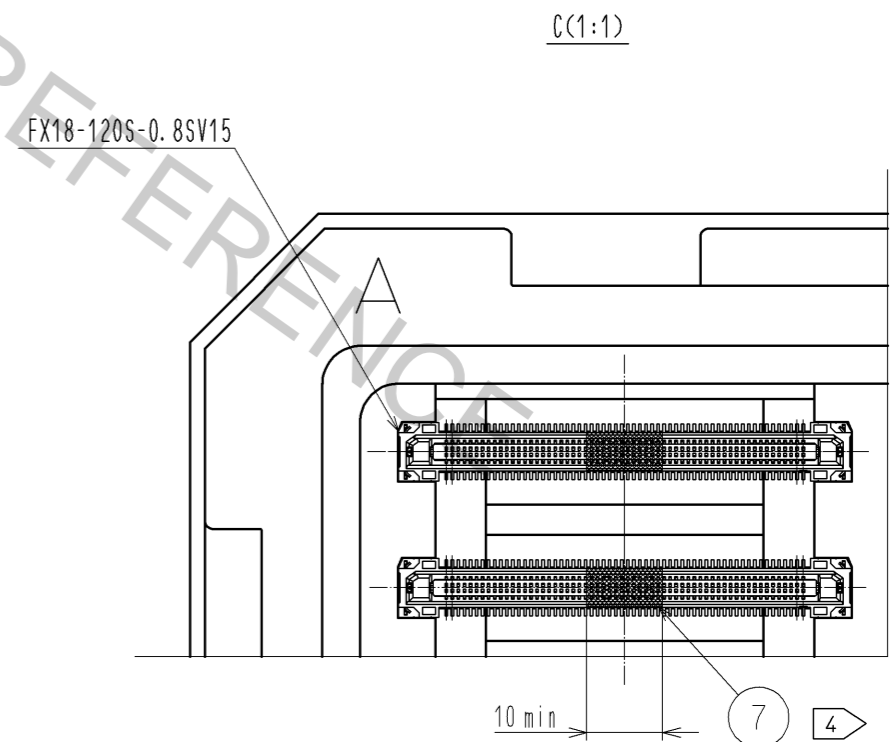
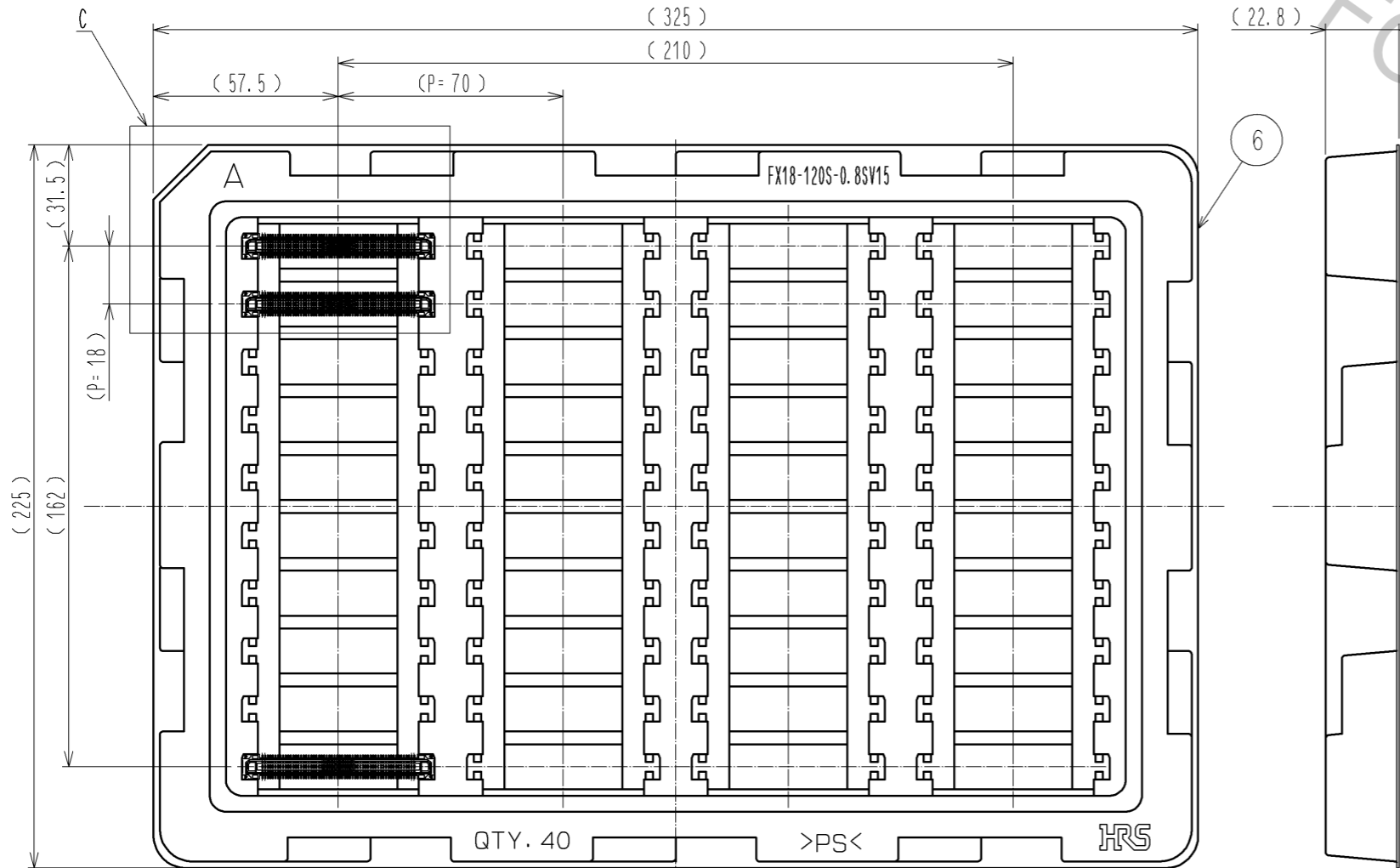


5 DRAWING FOR PACKING(1:2)

8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES. BE SURE TO CONNECT TO THE SAME CIRCUIT.



<b>HRS</b>	DRAWING NO.	EDC3-334389-00	1/2
	PART NO.	FX18-120S-0.8SV15	
	CODE NO.	CL579-0029-1-00	